

AQ3522-01LTG, 0.15pF 22kV bidirectional TVS diode



Description

The AQ3522 integrates ultra low capacitance diodes to provide protection for electronic equipment that may experience destructive electrostatic discharges (ESD). This robust component can safely absorb repetitive ESD strikes above the maximum level specified in the IEC 61000-4-2 international standard (Level 4, $\pm 8\text{kV}$ contact discharge) without performance degradation. The extremely low loading capacitance also makes it ideal for protecting high speed signal pins such as V-By-One®, HDMI, USB3.0, USB2.0, and IEEE 1394.

Pinout



Features

- ESD, IEC 61000-4-2, $\pm 22\text{kV}$ contact, $\pm 30\text{kV}$ air
- EFT, IEC 61000-4-4, 40A ($t_p = 5/50\text{ns}$)
- Lightning, 2.5A (8/20 μs as defined in IEC 61000-4-5 2nd edition)
- Low capacitance of 0.15pF (TYP) at 3GHz
- ESD, ISO 10605, 330pF 330 Ω , $\pm 21\text{kV}$ contact, $\pm 23\text{kV}$ air
- Facilitates excellent signal integrity
- PPAP capable
- AEC-Q101 qualified
- Halogen free, Lead free and RoHS compliant
- Moisture Sensitivity Level (MSL -1)

Functional Block Diagram



Applications

- Ultra-high speed data lines
- USB 3.1, 3.0, 2.0
- HDMI 2.0, 1.4a, 1.3
- DisplayPort™
- V-by-One®
- LVDS interfaces
- Automotive application
- Consumer, mobile and portable electronics
- Tablet PC and external storage with high speed interfaces
- Applications requiring high ESD performance in small packages

Absolute Maximum Ratings

Symbol	Parameter	Value	Units
I_{PP}	Peak Current ($t_p=8/20\mu s$)	2.5	A
T_{OP}	Operating Temperature	-45 to 150	°C
T_{STOR}	Storage Temperature	-55 to 150	°C

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the component. This is a stress only rating and operation of the component at these or any other conditions above those indicated in the operational sections of this specification is not implied.

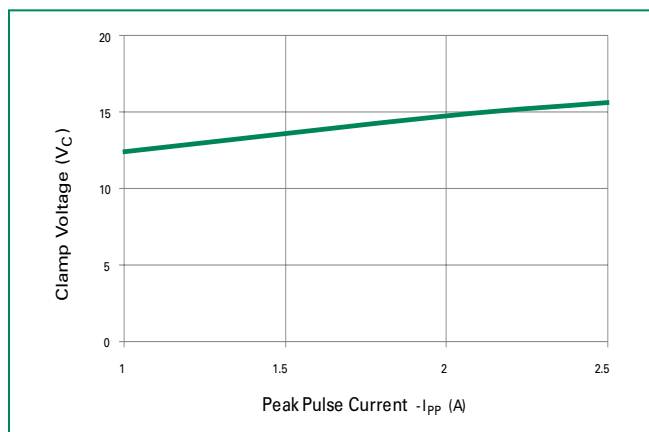
Electrical Characteristics - ($T_{OP}=25^{\circ}C$)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Reverse Standoff Voltage	V_{RWM}	$I_R=1\mu A$			5	V
Breakdown Voltage	V_{BR}	$I_R=1mA$	8.5	9.2		V
Reverse Leakage Current	I_{LEAK}	$V_R=5V$		0.02	0.1	μA
Clamp Voltage ¹	V_C	$I_{PP}=2.5A$, $t_p=8/20\mu s$, I/O to I/O		15.5	18	V
Dynamic Resistance ²	R_{DYN}	TLP, $t_p=100ns$, I/O to I/O		1.2		Ω
ESD Withstand Voltage ¹	V_{ESD}	IEC 61000-4-2 (Contact)	± 22			kV
		IEC 61000-4-2 (Air)	± 30			kV
Diode Capacitance ^{1,3}	$C_{I/O-I/O}$	Reverse Bias=0V, $f=3GHz$		0.15		pF

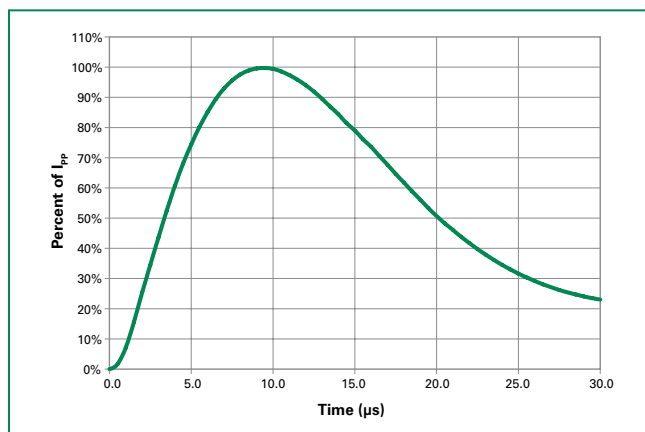
Note:

- Parameter is guaranteed by design and/or component characterization.
- Transmission Line Pulse (TLP) with 100ns width, 2ns rise time, and average window $t_1=70ns$ to $t_2=90ns$.
- Package sizes larger than 0201 can add parasitic capacitance, inductance and resistance.

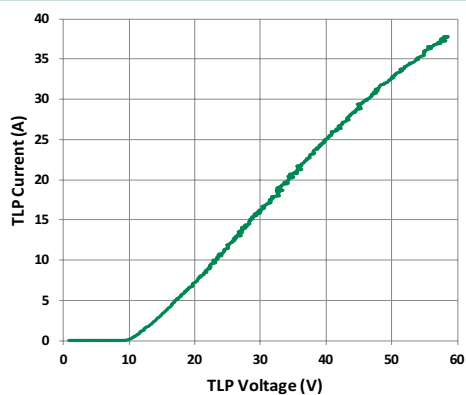
Clamping voltage vs. I_{PP} for 8/20 μs waveshape



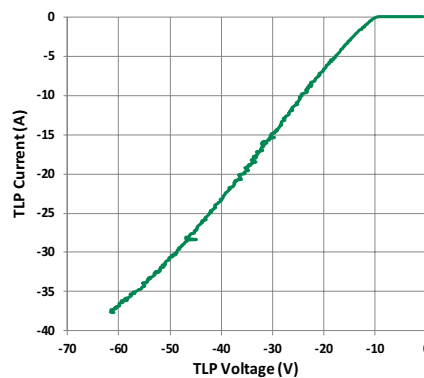
8/20 μs Pulse Waveform



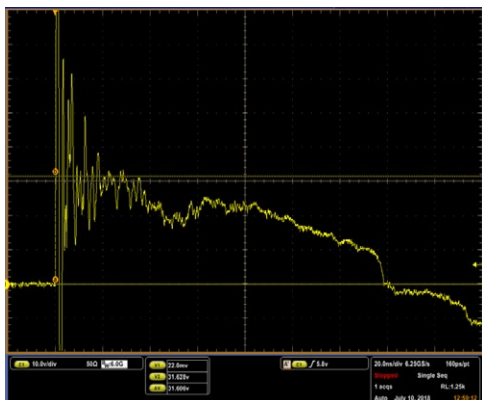
Positive Transmission Line Pulsing (TLP) Plot



Negative Transmission Line Pulsing (TLP) Plot



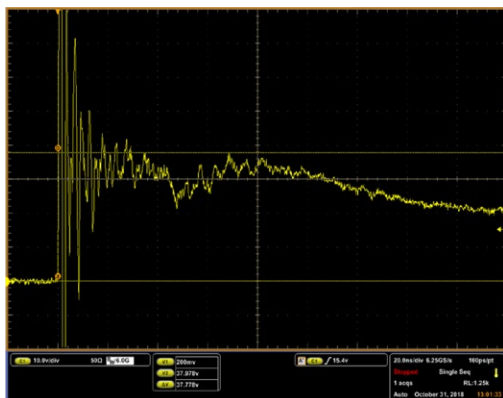
IEC 61000-4-2 +8 kV Contact ESD Clamping Voltage



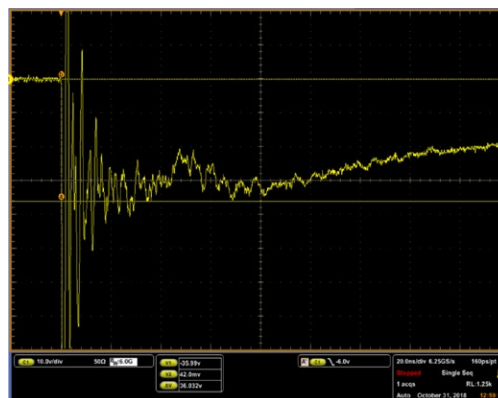
IEC 61000-4-2 -8 kV Contact ESD Clamping Voltage



ESD ISO10605 +8 kV Contact ESD Clamping Voltage

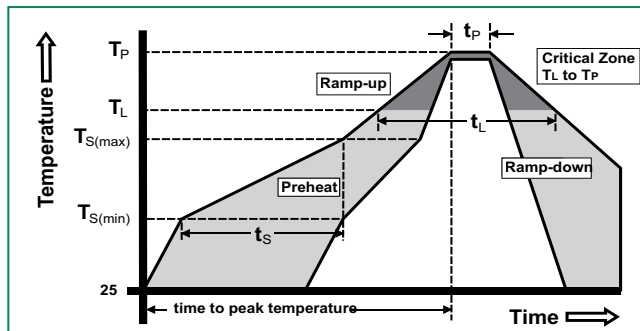


ESD ISO10605 -8 kV Contact ESD Clamping Voltage

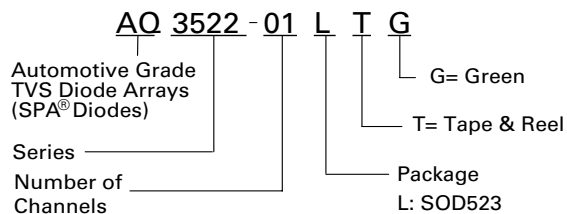


Soldering Parameters

Reflow Condition		Pb – Free assembly
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus) Temp (T_L) to peak		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes Max.
Do not exceed		260°C



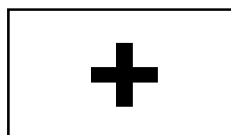
Part Numbering System



Product Characteristics

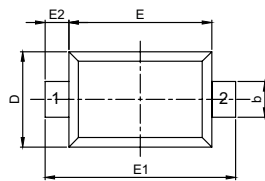
Lead Plating	Matte Tin
Lead Material	Copper Alloy
Lead Coplanarity	0.004 inches(0.102mm)
Substrate Material	Silicon
Body Material	Molded Compound
Flammability	UL Recognized compound meeting flammability rating V-0

Part Marking System

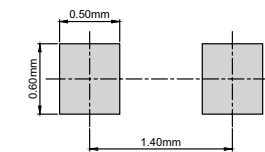
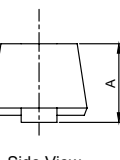
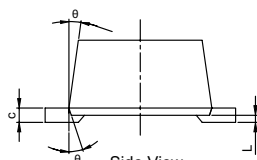


Ordering Information

Part Number	Package	Min. Order Qty.
AQ3522-01LTG	SOD523	5000

Package Dimensions — SOD-523


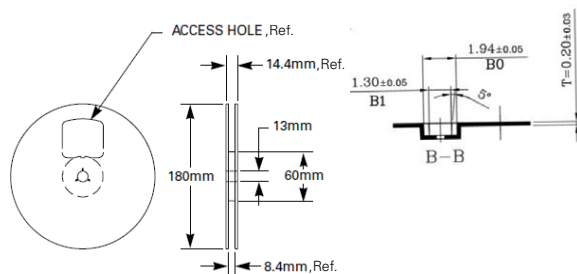
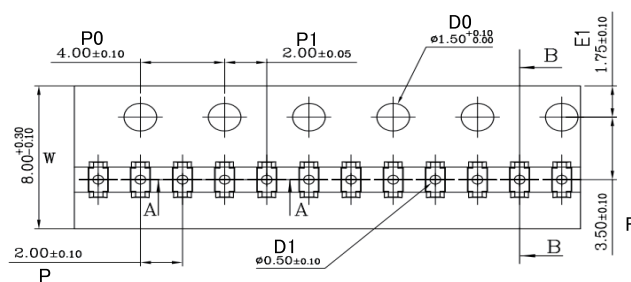
Top View



Recommended Soldering pad layout

Drawing#: L01-B

Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A	0.51	0.77	0.020	0.030
A1	0.50	0.70	0.020	0.028
b	0.25	0.35	0.010	0.014
c	0.08	0.15	0.003	0.006
D	0.70	0.90	0.028	0.035
E	1.10	1.30	0.043	0.051
E1	1.50	1.70	0.059	0.067
E2	0.20 REF		0.001 REF	
L	0.01	0.07	0.000	0.003
θ	7° REF		7° REF	

Embossed Carrier Tape & Reel Specification — SOD-523


8mm TAPE AND REEL

Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A0	0.91	1.01	0.036	0.040
B0	1.89	1.99	0.074	0.078
D0	1.50	1.60	0.059	0.063
D1	0.40	0.60	0.016	0.024
E1	1.65	1.85	0.065	0.073
F	3.40	3.60	0.134	0.142
P0	3.90	4.10	0.154	0.161
P	1.90	2.10	0.075	0.083
P1	1.95	2.05	0.077	0.081
K0	0.68	0.78	0.027	0.031
T	0.17	0.23	0.007	0.009
W	7.90	8.30	0.311	0.327

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Specifications are subject to change without notice.

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